INTEGRATED CIRCUITS

DATA SHEET

74LV245Octal bus transceiver (3-State)

Product specification Supersedes data of 1997 Feb 19 IC24 Data Handbook







Philips Semiconductors Product specification

Octal bus transceiver (3-State)

74LV245

FEATURES

• Wide operating voltage: 1.0 to 5.5 V

Optimized for low voltage applications: 1.0 to 3.6 V

Accepts TTL input levels between V_{CC} = 2.7 V and V_{CC} = 3.6 V

 Typical V_{OLP} (output ground bounce) < 0.8 V at V_{CC} = 3.3 V, $T_{amb} = 25^{\circ}C$

 Typical V_{OHV} (output V_{OH} undershoot) > 2 V at V_{CC} = 3.3 V, $T_{amb} = 25^{\circ}C$

Output capability: bus driver

I_{CC} category: MSI

DESCRIPTION

The 74LV245 is a low-voltage Si-gate CMOS device and is pin and function compatible with 74HC/HCT245.

The 74LV245 is an octal transceiver featuring non-inverting 3-State bus compatible outputs in both send and receive directions. The 74LV245 features an output enable (OE) input for easy cascading and a send/receive (DIR) input for direction control. OE controls the outputs so that the buses are effectively isolated.

QUICK REFERENCE DATA

GND = 0 V; $T_{amb} = 25^{\circ}C$; $t_r = t_f \le 2.5 \text{ ns}$

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t _{PHL} /t _{PLH}	Propagation delay A_n to B_n ; B_n to A_n	$C_L = 15 \text{ pF};$ $V_{CC} = 3.3 \text{ V}$	7.0	ns
C _I	Input capacitance		3.5	pF
C _{I/O}	Input/output capacitance		10	pF
C _{PD}	Power dissipation capacitance per buffer	$V_{CC} = 3.3 \text{ V}$ V _I = GND to V _{CC} , note 1	40	pF

NOTE:

 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$ where:

 $\begin{aligned} &f_i = \text{input frequency in MHz; } C_L = \text{output load capacitance in pF;} \\ &f_o = \text{output frequency in MHz; } V_{CC} = \text{supply voltage in V;} \end{aligned}$

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #	
20-Pin Plastic DIL	-40°C to +125°C	74LV245 N	74LV245 N	SOT146-1	
20-Pin Plastic SO	-40°C to +125°C	74LV245 D	74LV245 D	SOT163-1	
20-Pin Plastic SSOP Type II	-40°C to +125°C	74LV245 DB	74LV245 DB	SOT339-1	
20-Pin Plastic TSSOP Type I	-40°C to +125°C	74LV245 PW	74LV245PW DH	SOT360-1	

PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
1	DIR	Direction
2, 3, 4, 5, 6, 7, 8, 9	A ₀ to A ₇	Data inputs/outputs
10	GND	Ground (0 V)
18, 17, 16, 15, 14, 13, 12, 11	B ₀ to B ₇	Data inputs/outputs
19	ŌĒ	Output enable input (active LOW)
20	V _{CC}	Positive supply voltage

FUNCTION TABLE

INP	UTS	INPUTS/OUTPUT				
ŌĒ	DIR	A _n	B _n			
L	L	A = B	Inputs			
L	Н	Inputs	B = A			
Н	Х	Z	Z			

NOTES:

HIGH voltage level LOW voltage level =

X Z don't care

high impedance OFF-state

^{1.} C_{PD} is used to determine the dynamic power dissipation (P_D in μW)

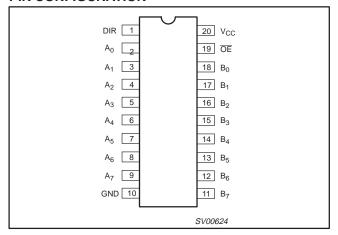
 $[\]sum$ (C_L × V_{CC}² × f_o) = sum of the outputs.

Philips Semiconductors Product specification

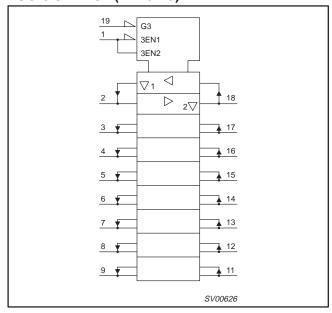
Octal bus transceiver (3-State)

74LV245

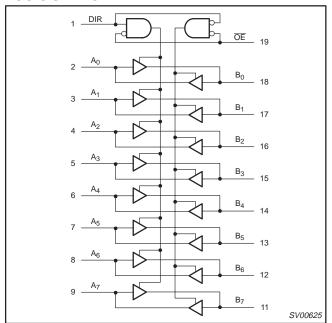
PIN CONFIGURATION



LOGIC SYMBOL (IEEE/IEC)



LOGIC SYMBOL



1998 Apr 20

3

74LV245

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP.	MAX	UNIT
V _{CC}	DC supply voltage	See Note 1	1.0	3.3	5.5	V
VI	Input voltage		0	-	V _{CC}	V
Vo	Output voltage		0	-	V _{CC}	V
T _{amb}	Operating ambient temperature range in free air	See DC and AC characteristics	-40 -40		+85 +125	°C
t _r , t _f	Input rise and fall times	$\begin{array}{c} V_{CC} = 1.0V \text{ to } 2.0V \\ V_{CC} = 2.0V \text{ to } 2.7V \\ V_{CC} = 2.7V \text{ to } 3.6V \\ V_{CC} = 3.6V \text{ to } 5.5V \end{array}$	- - - -	- - -	500 200 100 50	ns/V

NOTE

ABSOLUTE MAXIMUM RATINGS^{1, 2}

In accordance with the Absolute Maximum Rating System (IEC 134). Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
± I _{IK}	DC input diode current	$V_{I} < -0.5 \text{ or } V_{I} > V_{CC} + 0.5V$	20	mA
± I _{OK}	DC output diode current	$V_{O} < -0.5 \text{ or } V_{O} > V_{CC} + 0.5V$	50	mA
± 1 ₀	DC output source or sink current – bus driver outputs	-0.5V < V _O < V _{CC} + 0.5V	35	mA
±I _{GND} , ±I _{CC}	DC V _{CC} or GND current for types with – bus driver outputs		70	mA
T _{stg}	Storage temperature range		-65 to +150	°C
P _{TOT}	Power dissipation per package – plastic DIL – plastic mini-pack (SO) – plastic shrink mini-pack (SSOP and TSSOP)	for temperature range: -40 to +125°C above +70°C derate linearly with 12 mW/K above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	750 500 400	mW

NOTES

The LV is guaranteed to function down to V_{CC} = 1.0V (input levels GND or V_{CC}); DC characteristics are guaranteed from V_{CC} = 1.2V to V_{CC} = 5.5V.

^{1.} Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

^{2.} The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

Philips Semiconductors Product specification

Octal bus transceiver (3-State)

74LV245

DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions. Voltages are referenced to GND (ground = 0V).

SYMBOL PARAMETE					LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS	-40	°C to +8	5°C	-40°C to	+125°C	UNIT
			MIN	TYP ¹	MAX	MIN	MAX	1
		V _{CC} = 1.2V	0.9			0.9		
VIH	HIGH level Input	V _{CC} = 2.0V	1.4			1.4] _v
VIН	voltage	V _{CC} = 2.7 to 3.6V	2.0			2.0] `
		$V_{CC} = 4.5 \text{ to } 5.5 \text{V}$	0.7 * V _{CC}			0.7 * V _{CC}		
		V _{CC} = 1.2V			0.3		0.3	
V_{IL}	LOW level Input	V _{CC} = 2.0V			0.6		0.6	V
* IL	voltage	V _{CC} = 2.7 to 3.6V			0.8		0.8] `
		V _{CC} = 4.5 to 5.5			0.3 * V _{CC}		0.3 * V _{CC}	
		$V_{CC} = 1.2V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu A$		1.2				
	l <u>-</u>	$V_{CC} = 2.0V$; $V_I = V_{IH}$ or V_{IL} ; $-I_O = 100\mu A$	1.8	2.0		1.8		
V_{OH}	HIGH level output voltage; all outputs	$V_{CC} = 2.7V$; $V_I = V_{IH}$ or V_{IL} ; $-I_O = 100\mu A$	2.5	2.7		2.5		٧
	voltago, all outputo	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu A$	2.8	3.0		2.8		1
		$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu A$	4.3	4.5		4.3		1
.,	HIGH level output	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 8\text{mA}$	2.40	2.82		2.20		,,
V_{OH}	voltage; BUS driver outputs	$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 16\text{mA}$	3.60	4.20		3.50		\ \
		$V_{CC} = 1.2V; V_I = V_{IH} \text{ or } V_{IL;} I_O = 100 \mu A$		0				
		$V_{CC} = 2.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		0	0.2		0.2	1
V_{OL}	LOW level output voltage; all outputs	$V_{CC} = 2.7V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		0	0.2		0.2	V
	voltage, all outputs	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		0	0.2		0.2	1
		$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu\text{A}$		0	0.2		0.2	1
W	LOW level output voltage; BUS driver	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 8\text{mA}$		0.20	0.40		0.50	V
V_{OL}	outputs	$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 16\text{mA}$		0.35	0.55		0.65]
I _I	Input leakage current	$V_{CC} = 5.5V$; $V_I = V_{CC}$ or GND			1.0		1.0	μА
I _{OZ}	3-State output OFF-state current	V_{CC} = 5.5V; V_I = V_{IH} or V_{IL} ; V_O = V_{CC} or GND			5		10	μА
I _{CC}	Quiescent supply current; MSI	$V_{CC} = 5.5V; V_I = V_{CC} \text{ or GND}; I_O = 0$			20.0		160	μА
Δl _{CC}	Additional quiescent supply current	$V_{CC} = 2.7V$ to 3.6V; $V_I = V_{CC} - 0.6V$			500		850	μА

5

NOTE:1. All typical values are measured at T_{amb} = 25°C.

74LV245

AC CHARACTERISTICS

GND = 0V; $t_r = t_f \le 2.5$ ns; $C_L = 50$ pF; $R_L = 1$ K Ω

			CONDITION			LIMITS			
SYMBOL	PARAMETER	WAVEFORM	CONDITION	_	40 to +85 °	C	-40 to	+125 °C	UNIT
			V _{CC} (V)	MIN	TYP ¹	MAX	MIN	MAX	
			1.2		45	28			
	Propagation delay	l [2.0		15	28		34	
t _{PHL} /t _{PLH}	A_n to B_n ;	Figures 1	2.7		11	19		24	ns
	B _n to A _n	l [3.0 to 3.6		92	16		20	
			4.5 to 5.5		8 ³	11		14	
			1.2		55				
	3-State output enable time		2.0		19	31		39	
t _{PZH} /t _{PZL}	OE to A _n ;	Figures 2	2.7		14	23		29	ns
	OE to B _n	l [3.0 to 3.6		10 ²	18		23	
		l [4.5 to 5.5		8.5 ³	14		18	
			1.2		65				
	3-State output disable time	l [2.0	T	24	32		39	
t _{PHZ} /t _{PLZ}	OE to A _n ; OE to B _n	Figures 2	2.7		18	24		29	ns
	OE to B _n		3.0 to 3.6		14 ²	20		24	
			4.5 to 5.5		11.5 ³	16		19	

NOTES:

- 1. Unless otherwise stated, all typical values are measured at $T_{amb} = 25^{\circ}C$
- 2. Typical values are measured at $V_{CC} = 3.3 \text{ V}$.
- 3. Typical values are measured at $V_{CC} = 5.0 \text{ V}$.

AC WAVEFORMS

 $V_M = 1.5 \text{ V at } V_{CC} \ge 2.7 \text{ V and } \le 3.6 \text{ V}$

 V_{M} = 0.5 V \times V $_{CC}$ at V $_{CC}$ < 2.7 V and \geq 4.5 V

 V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.

$$\begin{split} &V_X = V_{OL} + 0.3 \text{ V at } V_{CC} \geq 2.7 \text{ V and } \leq 3.6 \text{ V} \\ &V_X = V_{OL} + 0.1 \times V_{CC} \text{ at } V_{CC} < 2.7 \text{ V and } \geq 4.5 \text{ V} \\ &V_Y = V_{OH} - 0.3 \text{ V at } V_{CC} \geq 2.7 \text{ V and } \leq 3.6 \text{ V} \\ &V_Y = V_{OH} - 0.1 \times V_{CC} \text{ at } V_{CC} < 2.7 \text{ V and } \geq 4.5 \text{ V} \end{split}$$

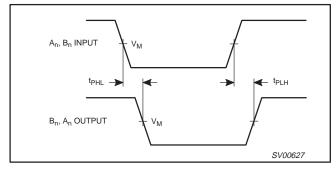


Figure 1. Input (A_n, B_n) to output (B_n, A_n) propagation delays and the output transition times.

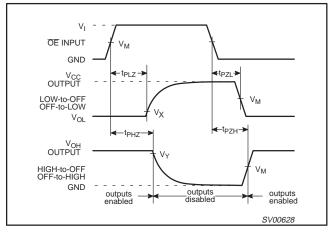


Figure 2. 3-State enable and disable times.

74LV245

TEST CIRCUIT

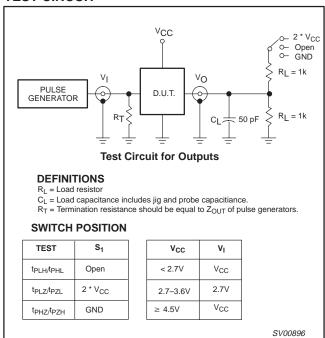
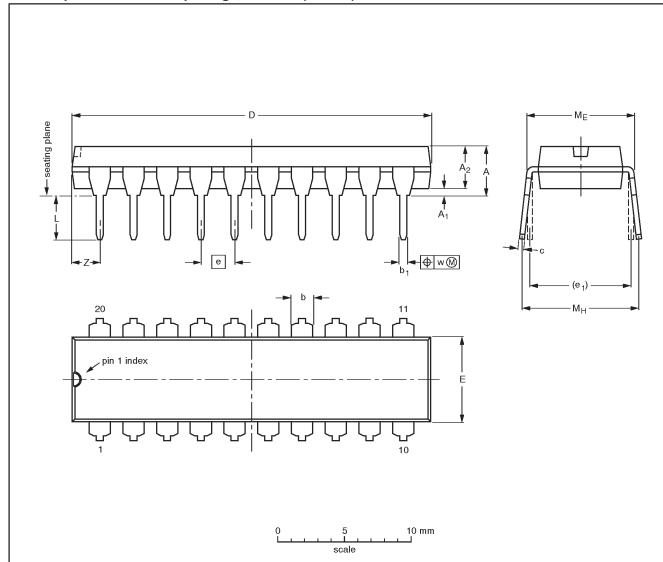


Figure 3. Load circuitry for switching times.

74LV245

DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

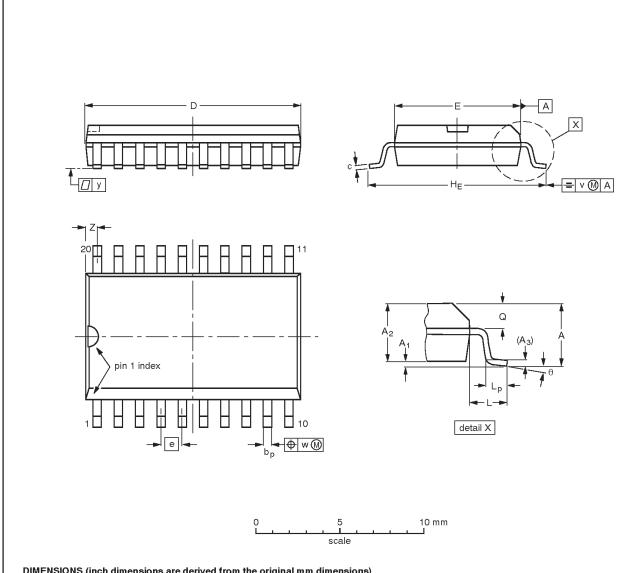
OUTLINE					EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT146-1			SC603			92-11-17 95-05-24	

1998 Apr 20 8

Product specification

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	Α1	A ₂	A ₃	bp	O	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	٧	w	у	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016		0.01	0.01	0.004	0.035 0.016	0°

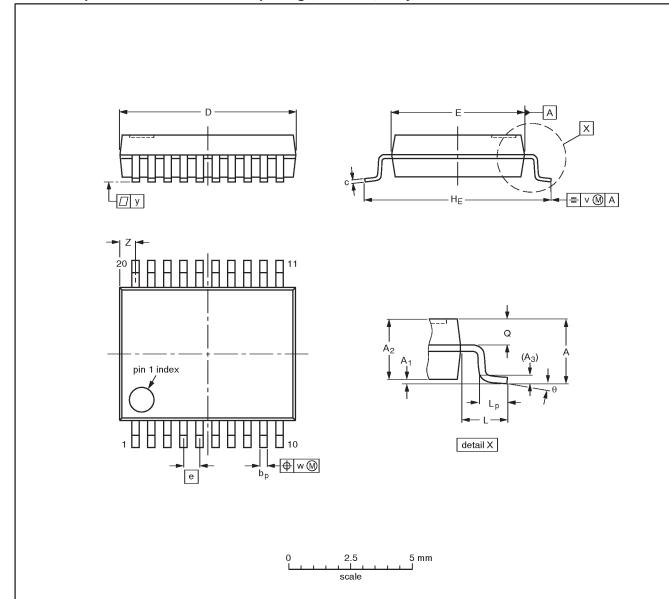
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE	TLINE REFERENCES				EUROPEAN	ISSUE DATE	
VERSION	IEC JEDEC		EIAJ		PROJECTION	ISSUE DATE	
SOT163-1	075E04	MS-013AC				-92-11-17 95-01-24	

74LV245

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	A ₃	bр	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

Note

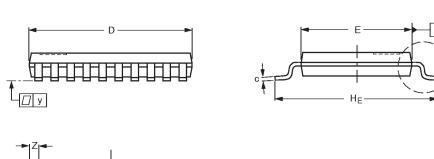
1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

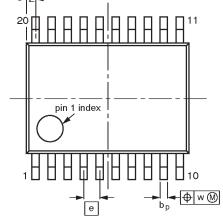
OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT339-1		MO-150AE				93-09-08 95-02-04	

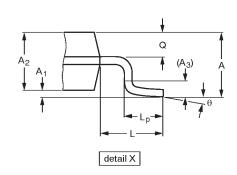
74LV245

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1









DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	A ₃	рb	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUEDATE
SOT360-1		MO-153AC				-93-06-16 95-02-04

74LV245

DEFINITIONS						
Data Sheet Identification	Product Status	Definition				
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.				
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.				
Product Specification	Full Production	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.				

Philips Semiconductors and Philips Electronics North America Corporation reserve the right to make changes, without notice, in the products, including circuits, standard cells, and/or software, described or contained herein in order to improve design and/or performance. Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no license or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified. Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

LIFE SUPPORT APPLICATIONS

Philips Semiconductors and Philips Electronics North America Corporation Products are not designed for use in life support appliances, devices, or systems where malfunction of a Philips Semiconductors and Philips Electronics North America Corporation Product can reasonably be expected to result in a personal injury. Philips Semiconductors and Philips Electronics North America Corporation customers using or selling Philips Semiconductors and Philips Electronics North America Corporation Products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors and Philips Electronics North America Corporation for any damages resulting from such improper use or sale.

Philips Semiconductors 811 East Arques Avenue P.O. Box 3409 Sunnyvale, California 94088–3409 Telephone 800-234-7381 © Copyright Philips Electronics North America Corporation 1998 All rights reserved. Printed in U.S.A.

print code Date of release: 05-96

Document order number: 9397-750-04438

Let's make things better.

Philips Semiconductors



